

My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and sole inventor if only one name is listed at 201 below, or an original, first and joint inventor if plural names are listed at 201 et seq. below, of the subject matter which is claimed and for which a patent is sought on the invention entitled

## RESIDUE REMOVERS FOR ELECTROHYDRODYNAMIC CLEANING OF SEMICONDUCTORS

and for which a patent application:						
☐ is attached hereto and includes a	mendment(s) filed on (if applic	cable)				
was filed in the United States on Patent Application Serial No. 10/802	March 18, 2004 and is iden ,780	tified by <b>Morgan, Lew</b>	is & Bockius Ll	LP Docket 6093'	7-0178-US, and U.S.	
I hereby state that I have reviewed and amendment referred to above						
I acknowledge the duty to disclose info Regulations, §1.56.	ormation known to me to be	material to patentability	as defined in Ti	tle 37, Code of F	ederal	
I hereby claim foreign priority benefits certificate listed below and have also it of the application on which priority is of	dentified below any foreign a	es Code, §119(a)-(d) of application for patent or	any foreign appl inventor's certif	ication(s) for pate icate having a fil	ent or inventor's ing date before that	
EARLIEST FOREIGN AF	PLICATION(S), IF ANY, F	FILED PRIOR TO THE	FILING DATE	OF THE APPLI	CATION	
APPLICATION NUMBER	COUNTRY		DATE OF FILING (day, month, year)		PRIORITY CLAIMED	
				YES □	NO □	
				YES □	ИО □	
I hereby claim the benefit under Title 3 PROVISIONAL APPLIC		(e) of any United States		lication(s) listed	below.	
60/455,439	March 18, 2003					
· · · · · · · · · · · · · · · · · · ·					·	
I hereby claim the benefit under Title 3 of each of the claims of this application 35, United States Code §112, I acknow	n is not disclosed in the prior ledge the duty to disclose in	United States applicati formation known to me	on in the manner which is material	r provided by the al to patentability	first paragraph of Ti as defined in Title 3	
Code of Federal Regulations, §1.56 wh filing date of this application:	nen became avanable betwee	on the many care or the				
Code of Federal Regulations, §1.56 wh filing date of this application:  NON-PROVISIONAL			STAT	<u> </u>		
Code of Federal Regulations, §1.56 wh filing date of this application:	FILING DATE	PATENTED		rus	ABANDONED	

for use only when the application is assigned to a company, partnership or other organization.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

		T				
2 0 1	FULL NAME	LAST NAME	FIRST NAME	MIDDLE NAME	MIDDLE NAME	
	OF INVENTOR	SMALL	Robert	J.		
	RESIDENCE &	спу	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENS	HIP	
	CITIZENSHIP	Tucson	AZ	United States	· ·	
	POST OFFICE	STREET	СІТУ	STATE OR COUNTRY	ZIP CODE	
	POST OFFICE ADDRESS	5198 S. Civano Boulevard	Tucson	AZ	85747	
L		SIGNATURE OF INVENTOR SMAL	June 21, 2004			
2 0 2	FULL NAME OF INVENTOR	LAST NAME	FIRST NAME	MADDLE NAME		
	RESIDENCE & CITIZENSHIP	СПУ	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP		
	POST OFFICE ADDRESS	STREET	СПУ	STATE OR COUNTRY	ZIP CODE	
		SIGNATURE OF INVENTOR L	DATE			
2 0 3	FULL NAME OF INVENTOR	LAST NAME	FIRST NAME	MIDDLE NAME		
	RESIDENCE & CITIZENSHIP	CITY	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP		
	POST OFFICE ADDRESS	STREET	спу	STATE OR COUNTRY	ZIP CODE	
		SIGNATURE OF INVENTOR 203	DATE			
2 0 4	FULL NAME OF INVENTOR	LAST NAME	FIRST NAME	MIDDLE NAME		
	RESIDENCE & CITIZENSHIP	СПУ	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP		
	POST OFFICE ADDRESS	STREET	СПҮ	STATE OR COUNTRY	ZIP CODE	
		SIGNATURE OF INVENTOR 204	DATE			